





Name	Designator	Quantity	MPN	Vendor	Footprint	Description	Voltage	Value
MLCC	C1, C2	2			CAPC1608X08L	Multilayer Ceramic Capacitor	16V	1uF
MLCC	Cbst	1			CAPC1608X08L	Multilayer Ceramic Capacitor	25V	470nF
MLCC	Cbyp	1			CAPC2012X12L	Multilayer Ceramic Capacitor	25V	100nF
MLCC	Cff	1			CAPC1608X08L	Multilayer Ceramic Capacitor	6.3V	100pF
MLCC	Cin1, Cin2	2	C3216X5R1E476M160AC	TDK	CAPC3225X25L	Multilayer Ceramic Capacitor	25V	47uF
CAPACITOR	Cout1, Cout2	2	EEFCS1A470R	Panasonic	CAPMP7343X11L	Electrolytic Capacitor	6.3V	47uF
MLCC	Css	1			CAPC1608X08L	Multilayer Ceramic Capacitor	25V	68nF
MLCC	Cvcc	1			CAPC1608X08L	Multilayer Ceramic Capacitor	16V	2.2uF
LM3150MH/NOPB	IC1	1	LM3150MH/NOPB	Texas Instruments	MXA14A	Buck controller		
M74VHC1GT125	IC2	1			SOT65P210X100-5L	Level shifter non inverting		
NCP551	IC3	1			SOT95P260X90-5L			
744313330	L1	1	744313330	Wurth Elektronik	WE-HCI_1335	Inductor		6.8uH
STL90N6F7	M1	1	CSD17579Q5A	Texas Instruments	TRANS_NexFET_Q5A	N Channel MOSFET		
STL90N6F7	M2	1	CSD18537NQ5A	Texas Instruments	TRANS_NexFET_Q5A	N Channel MOSFET		
RES0603	Rb1	1			RESC1608X03L	Chip Resistor		10K
RES0603	RiLim	1			RESC1608X03L	Chip Resistor		2.21K
RES0603	Ron	1			RESC1608X03L	Chip Resistor		240k
RES0603	Rt1	1			RESC1608X03L	Chip Resistor		91k
RES0603	Rt2	1			RESC1608X03L	Chip Resistor		3M

## Design Rules Verification Report

Filename : C:\Dev\wifi-christmas-tree-lights\pcbs\buck4\buck4.PcbDoc

Warnings 0  
Rule Violations 0

Warnings	
Total	0

Rule Violations	
Clearance Constraint (Gap=0.127mm) (All),(All)	0
Short-Circuit Constraint (Allowed=No) (All),(All)	0
Short-Circuit Constraint (Allowed=Yes) (InNet("GND")), (InNet("SGND"))	0
Un-Routed Net Constraint ( All )	0
Width Constraint (Min=0.127mm) (Max=2.54mm) (Preferred=0.127mm) (All)	0
Routing Via (Templates Used To Check Via: connector, gnd_stitch, signal_routing, v65h40m0mx0) (All)	0
Power Plane Connect Rule(Direct Connect )(Expansion=0.508mm) (Conductor Width=0.254mm) (Air Gap=0.254mm)	0
Hole Size Constraint (Min=0.025mm) (Max=4mm) (All)	0
Pads and Vias to follow the Drill pairs settings	0
Hole To Hole Clearance (Gap=0.254mm) (All),(All)	0
Minimum Solder Mask Sliver (Gap=0.2mm) (All),(All)	0
Net Antennae (Tolerance=0mm) (All)	0
Board Clearance Constraint (Gap=0mm) (Not (OnLayer("Top Overlay") Or OnLayer("Bottom Overlay")))	0
Component Clearance Constraint ( Horizontal Gap = 0.05mm, Vertical Gap = Infinite ) (All),(All)	0
Height Constraint (Min=0mm) (Max=25.4mm) (Preferred=12.7mm) (All)	0
Total	0